

Title of Change:	Back Grinding site change from onsemi Gresham to onsemi, ISMF Malaysia for select products
Effective date:	16 Oct 2023
Contact information:	Contact your local onsemi Sales Office or Adrian.Croitoru@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Backgrinding site change from onsemi Gresham to onsemi ISMF
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi, ISMF Malaysia	None

Description and Purpose:

onsemi would like to notify customers of a change in backgrind location for the devices listed in this Product Bulletin. The products in this notification are currently receiving backgrind in the wafer fab, onsemi, Gresham US (USR), but will be moved to our backgrind center of excellence in onsemi, ISMF Malaysia (ISMF). The equipment in USR is reaching the end of life, and will no longer be utilized once this transfer is complete. ISMF has production history spanning more than 10 years as the backgrind center of excellence, and similar wafers fabricated in USR (using the same wafer fabrication technology) are already receiving backgrind in ISMF.

Electrical characteristics have not changed.

Implementation will become effective for each listed device on date referenced in header of this document.

Site change	From	To
Back Grinding	onsemi, Gresham, Oregon (US)	onsemi, ISMF Malaysia

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

NCV20092DTBR2G	NCV20092DR2G	NCV20092DMR2G
NCV20082DTBR2G	NCV20082DR2G	NCV20082DMR2G
NCV20062DTBR2G	NCV20062DR2G	NCV20062DMR2G
NCV274DTBR2G	NCV20034DR2G	NCV20074DR2G
NCV274DR2G	NCV20074DTBR2G	